



Material Content Data Sheet



Sales Product Name		IPG20N10S4L-35		Issued		31. July 2018		
MA#		MA000940700						
Package		PG-TDSON-8-4		Weight*		96.57 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.028	1.06	1.06	10641	10641
chip_2	inorganic material	silicon	7440-21-3	1.028	1.06	1.06	10641	10641
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		139	
	non noble metal	iron	7439-89-6	0.045	0.05		463	
	non noble metal	copper	7440-50-8	44.654	46.26	46.32	462409	463011
	non noble metal	aluminium	7429-90-5	0.738	0.76	0.76	7638	7638
wire	non noble metal	aluminium	7429-90-5	0.738	0.76	0.76	7638	7638
	organic material	carbon black	1333-86-4	0.090	0.09		936	
encapsulation	plastics	epoxy resin	-	6.415	6.64		66433	
	inorganic material	silicondioxide	60676-86-0	38.672	40.05	46.78	400469	467838
leadfinish	non noble metal	tin	7440-31-5	1.308	1.35	1.35	13541	13541
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.048	0.05	0.05	497	498
solder	non noble metal	tin	7440-31-5	0.051	0.05		524	
	noble metal	silver	7440-22-4	0.063	0.07		655	
	non noble metal	lead	7439-92-1	2.415	2.50	2.62	25013	26192
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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